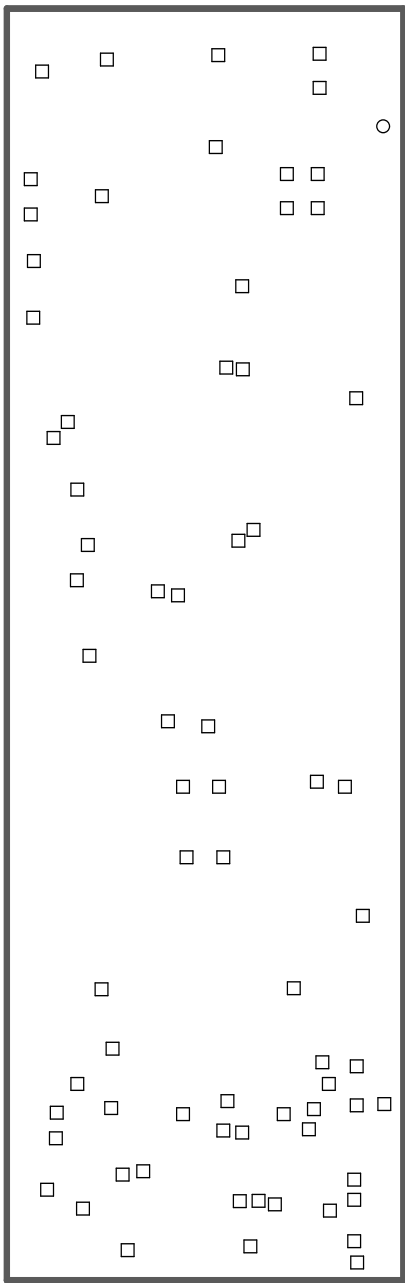



Symbol	Count	Hole Size	Plated	Hole Type	Drill Layer Pair	Via/Pad	Pad Shape
□	71	10.00mil (0.254mm)	PTH	Round	Top Layer - Bottom Layer	Via	Rounded
○	1	20.00mil (0.508mm)	PTH	Round	Top Layer - Bottom Layer	Via	Rounded
	72 Total						

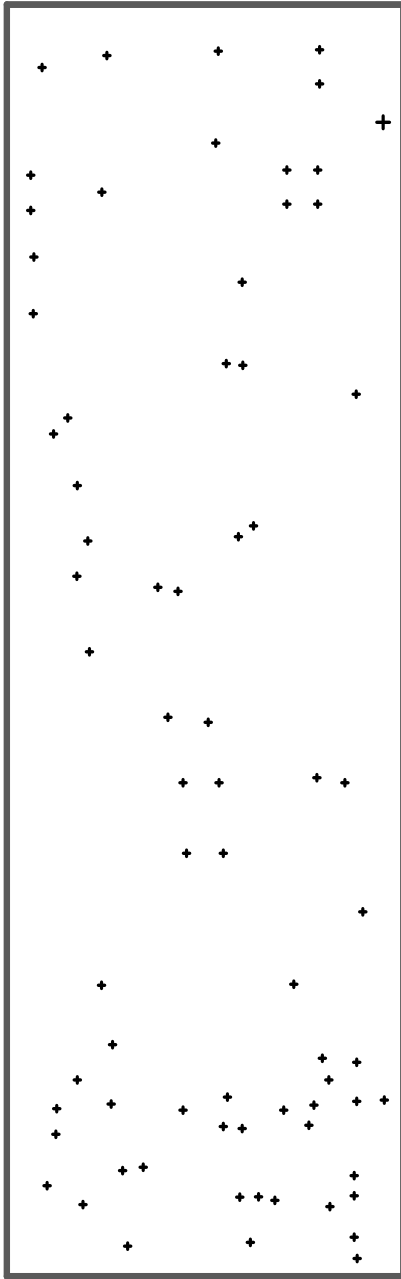
LAYERS: 2
MATERIAL: FR4, RoHS, 94v0
THICKNESS: 1.6mm (~62 mils)
FINISH: Gold (ENIG) RoHS
SILK SCREEN: White
SOLDER MASK: GREEN


>> IMPORTANT FABRICATION NOTES <<

- 1) Many pads have intentional undersize solder mask openings/oversize pads for physical strength.
- 2) Make top and bottom solder masks exactly as shown. Do _NOT_ "open-up" the solder mask layers. This design uses "solder-mask-defined-pads".
- 3) Silkscreened Legend (white) must be clean and clear. Silkscreen legend must have good registration. Silkscreen may be intentionally placed over bare copper. Do not clip silkscreen to solder mask layer.



 Crystalfontz 12412 East Saltese Avenue Spokane Valley, WA 99216 USA Tel: (509) 892-1200 http://www.crystalfontz.com Copyright © 2019 Crystalfontz America, Inc.	PROJECT CFA-10110 VERSION 0v0	
	PCB PCB10110 REVISION 0v0	DATE 2020-10-08
LAYER Drill Drawing/Notes	FILE NAME CFA10110_0v0.GD1	



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	PCB	REVISION	DATE		
	PCB10110	0v0	2020—10—08		
LAYER		FILE NAME			
Drill Guide		CFA10110_0v0.GG1			